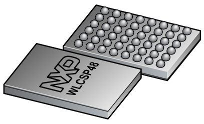


SOT1887-5

WLCSP48, wafer level chip-scale package; 48 bumps; 0.4 mm pitch, 2.51 mm x 3.55 mm x 0.525 mm body

24 March 2020

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP48
Package type industry code	WLCSP48
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	08-12-2017
Manufacturer package code	98ASA01165D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.48	2.51	2.54	mm
package width	3.52	3.55	3.58	mm
seated height	-	0.525	0.565	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	48	-	

2 Package outline

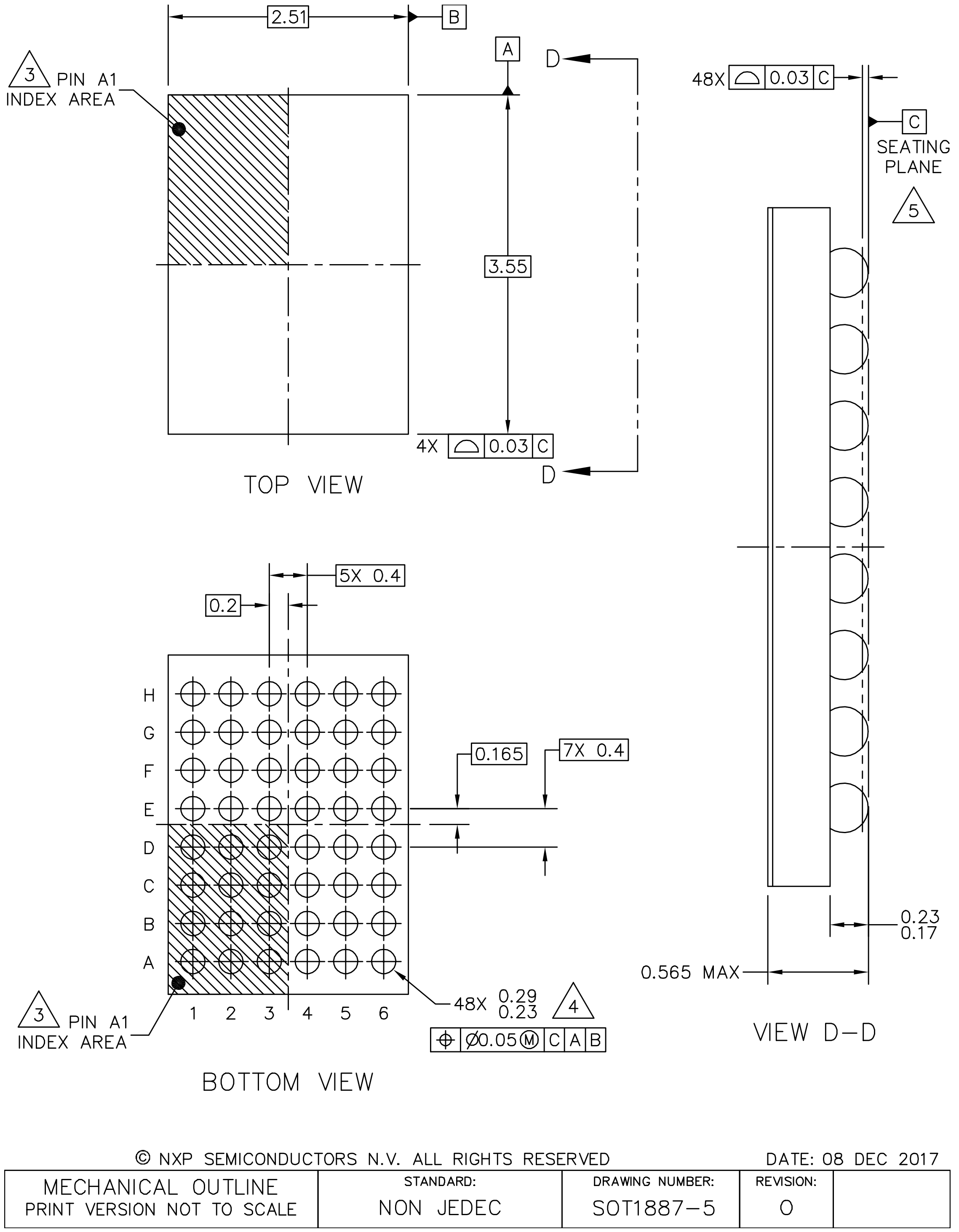
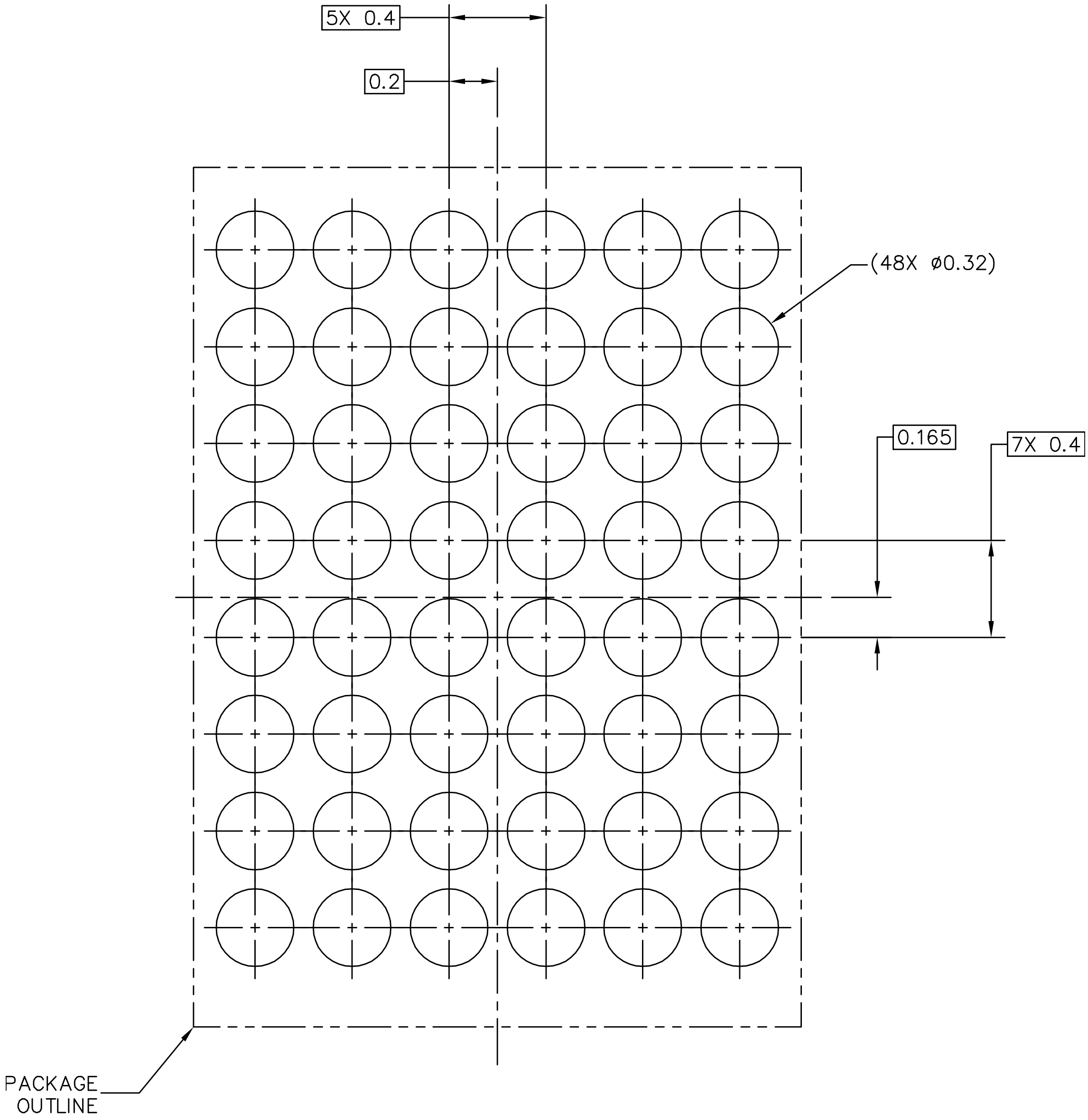


Figure 1. Package outline WLCSP48 (SOT1887-5)

3 Soldering



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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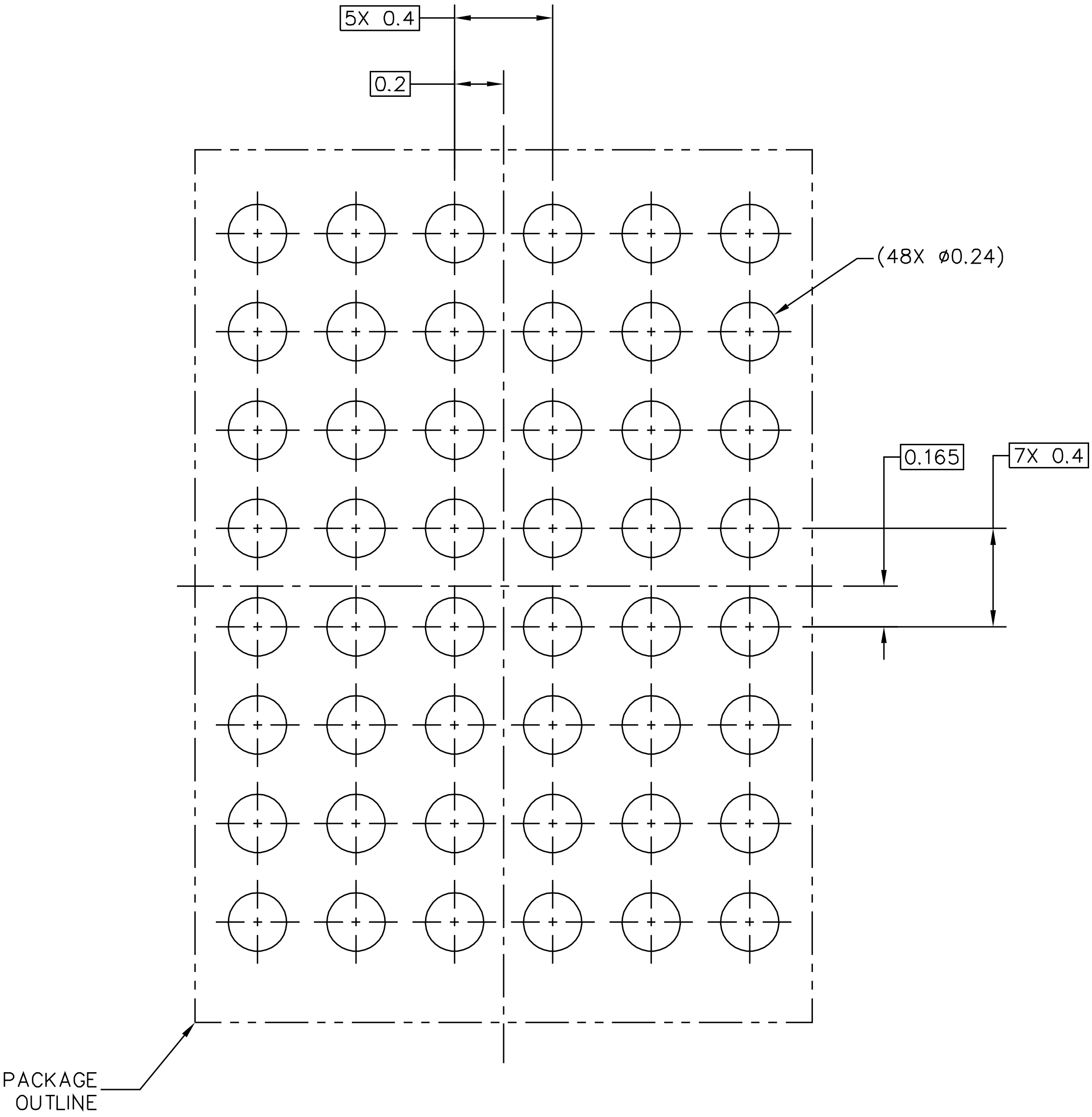
DATE: 08 DEC 2017

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: SOT1887-5	REVISION: 0	

Figure 2. Reflow soldering footprint part1 for WLCSP48 (SOT1887-5)



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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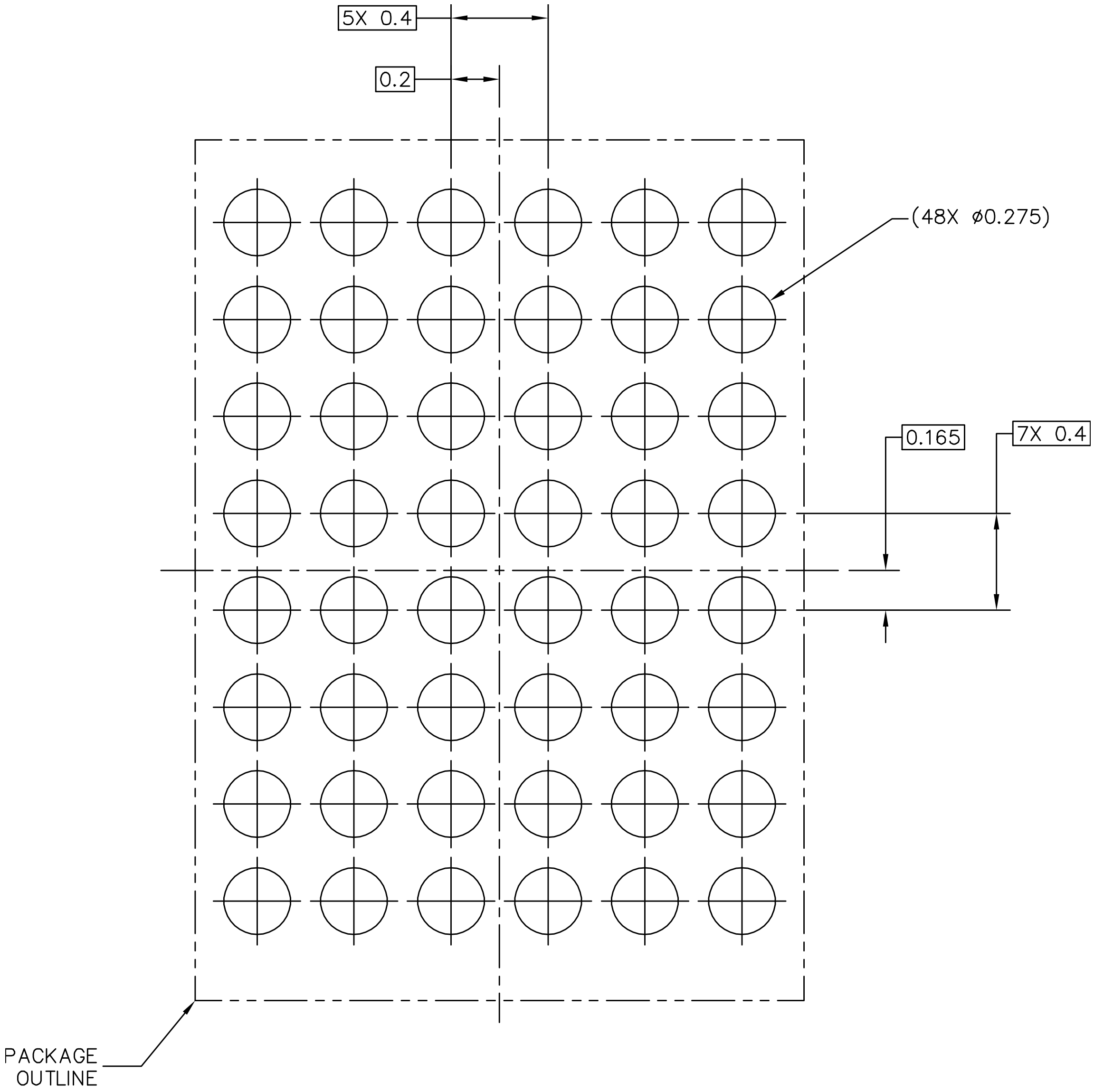
DATE: 08 DEC 2017

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: SOT1887–5	REVISION: 0	

Figure 3. Reflow soldering footprint part2 for WLCSP48 (SOT1887-5)



RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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DATE: 08 DEC 2017

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD:	DRAWING NUMBER:	REVISION:	
	NON JEDEC	SOT1887–5	0	

Figure 4. Reflow soldering footprint part3 for WLCSP48 (SOT1887-5)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M—1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. THIS PACKAGE HAS A BACK SIDE COATING THICKNESS OF 0.025.

DATE: 08 DEC 2017

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: SOT1887—5	REVISION: 0	

Figure 5. Package outline note WLCSP48 (SOT1887-5)

4 Legal information

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